

09/816,055

L Number	Hits	Search Text	DB	Time stamp
1	36	((("4630096") or ("4746960") or ("4827328") or ("4860166") or ("4866508") or ("4878991") or ("4884122") or ("4894115") or ("4907062") or ("4933042") or ("5049980") or ("5091769") or ("5111278") or ("5144747") or ("5250843") or ("5324687") or ("5426566") or ("5757072"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 15:33
2	3118	((438/618) or (438/622) or (438/107)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 15:34
3	2218	((438/618) or (438/622) or (438/107)).CCLS.) and @ad<20000324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 15:34
4	73	((438/618) or (438/622) or (438/107)).CCLS.) and @ad<20000324) and ((chip die) near4 expos\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 15:53
5	109	((438/618) or (438/622) or (438/107)).CCLS.) and @ad<20000324) and release\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:13
6	14	((438/618) or (438/622) or (438/107)).CCLS.) and @ad<20000324) and (release adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:15
7	67	((release adj layer) near4 (chip die)) and @ad<20000324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:43
8	52040	(chip die dice semiconductor) and @ad<20000324 and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:45
9	2552	((chip die dice semiconductor) near4 (expose exposed)) and @ad<20000324 and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:47
10	1580	((chip die dice semiconductor) near4 (expose exposed)) and @ad<20000324 and interconnect) and (via (through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:47
11	341	((chip die dice semiconductor) near4 (expose exposed)) and @ad<20000324 and (interconnect near4 (via (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/16 16:49